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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

PTO
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1. Name of conveying party(ies):

**YUNG-SHENG HUANG, CHIU-CHING LIN,
CHUN-HUNG LU AND RUEY-LIAN HWANG**

2. Name and address of receiving party(ies):

Name: **Taiwan Semiconductor Manufacturing Company**

Internal Address:

Street Address:

**121 Park Ave. 3
Science-Based Industrial Park
City: Hsin-Chu Zip:
Country: Taiwan, R.O.C.**

Additional name(s) or conveying party(ies) attached? Yes No

3. Nature of conveyance

- Assignment Merger
- Security Agreement Change of Name
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Execution Date: **11/19/99**

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: **11/19/99**

A. Patent Application No(s)

B. Patent No.(s)

Handwritten: 09/483934

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **GEORGE O. SAILE**
Internal Address: _____

Street Address: **20 MCINTOSH DRIVE**

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6. Total no. of applications and patents involved: **1**

7. Total fee (37 CFR 3.41): **\$ 40.00**

Enclosed

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STEPHEN B. ACKERMAN

Name of Person Signing

Signature

Jan. 12, 2000

Date

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Total number of pages comprising cover sheet: **3**

For U.S. and/or Foreign Rights

For Application or U.S. Patent

By Inventor(s) or Present Owner

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

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Type or print name of ASSIGNOR

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Republic of China
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Type or print name of ASSIGNOR

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Nationality

ASSIGNEE:

Taiwan Semiconductor Manufacturing Co. Ltd.

121 Park Ave. 3

Science-Based Industrial Park

Hsin-Chu, Taiwan, R.O.C.

Taiwan, R.O.C.

Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

- the entire right, title and interest
- an undivided _____ percent (____%) interest for the United States and its territorial possessions
(check the following box if foreign rights are also to be assigned)
- and in all foreign countries

in and to any and all improvements which are disclosed in the invention entitled:

A Novel Bonding Pad Structure To Prevent Inter-Metal Dielectric Cracking And To Improve Bondability

and which is found in

- (a) U.S. patent application executed on even date herewith
- (b) U.S. patent application executed on _____
- (c) U.S. application serial no. _____ filed on _____
- (d) U.S. patent no. _____ issued _____
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IN WITNESS WHEREOF, I / We have signed this

1/9 1999 (Date of signing)

WARNING Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Yung-Sheng Huang
Signature of ASSIGNOR(S)

Chin-Ching Lin

Chun-Hung Lin

Ruey-Ian Huang

If ASSIGNOR is a legal entity complete the following information

Type or print the name of the above person authorized to sign on behalf of ASSIGNOR

Title

Note: No witnessing, notarization or legalization is necessary. If the assignment is notarized or legalized then it will only be prima facie evidence (35 USC 261). Use next page if notarization is desired.

___Notarization of Legalization Page Added.